

SOT1535-1

LPGA144; plastic, low profile ball grid array; 144 balls; 1.0 mm pitch; 13 mm x 13 mm x 1.7 mm body

14 January 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LPGA144
Package type industry code	LPGA144
Package style descriptive code	LPGA (low profile ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	06-01-2016
Manufacturer package code	98ASA00222D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	13	-	mm
package width	-	13	-	mm
seated height	-	1.7	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	144	-	



LPGA144; plastic, low profile ball grid array; 144 balls; 1.0 mm pitch; 13 mm x 13 mm x 1.7 mm body

2 Package outline

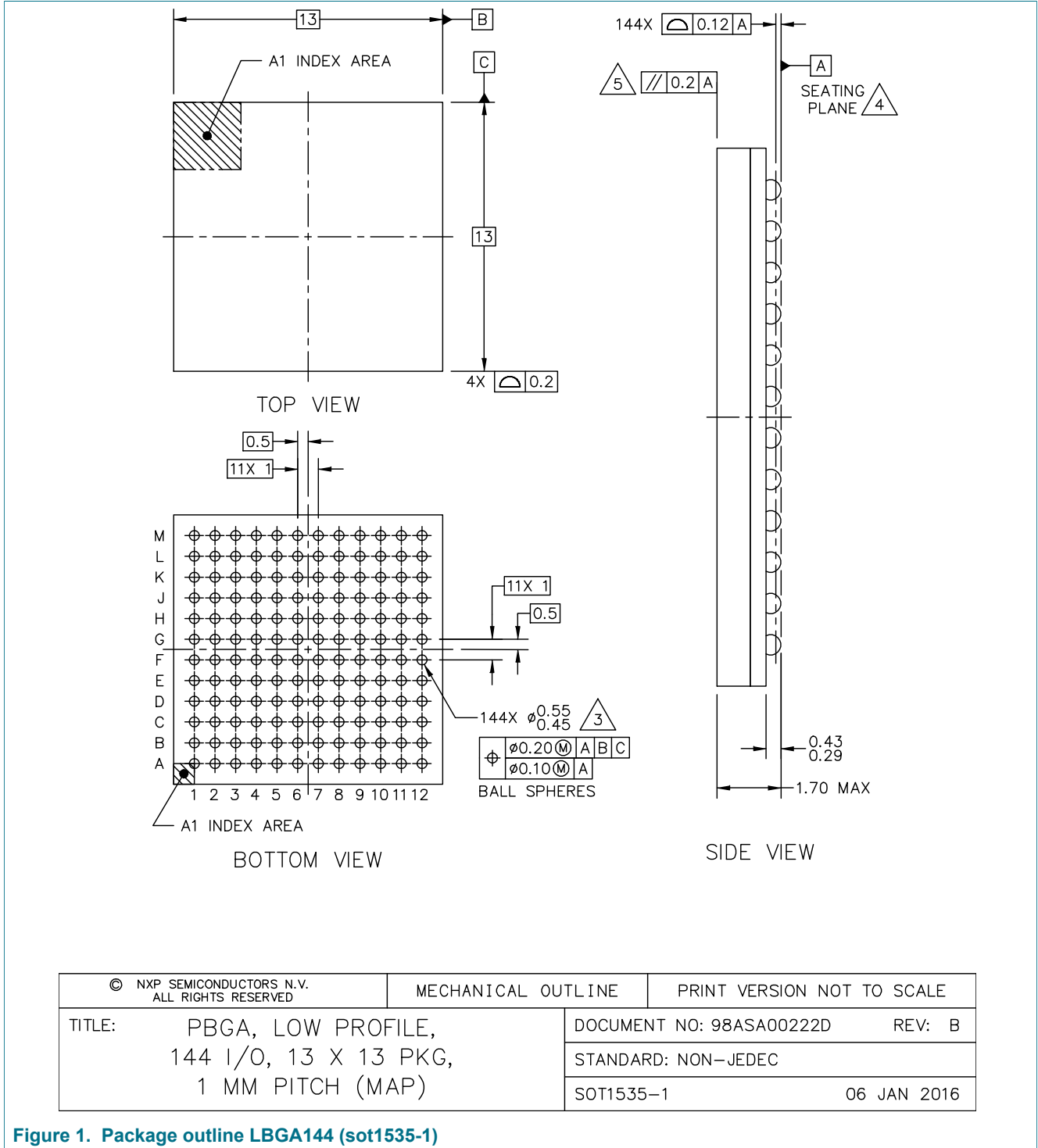


Figure 1. Package outline LPGA144 (sot1535-1)

3 Soldering

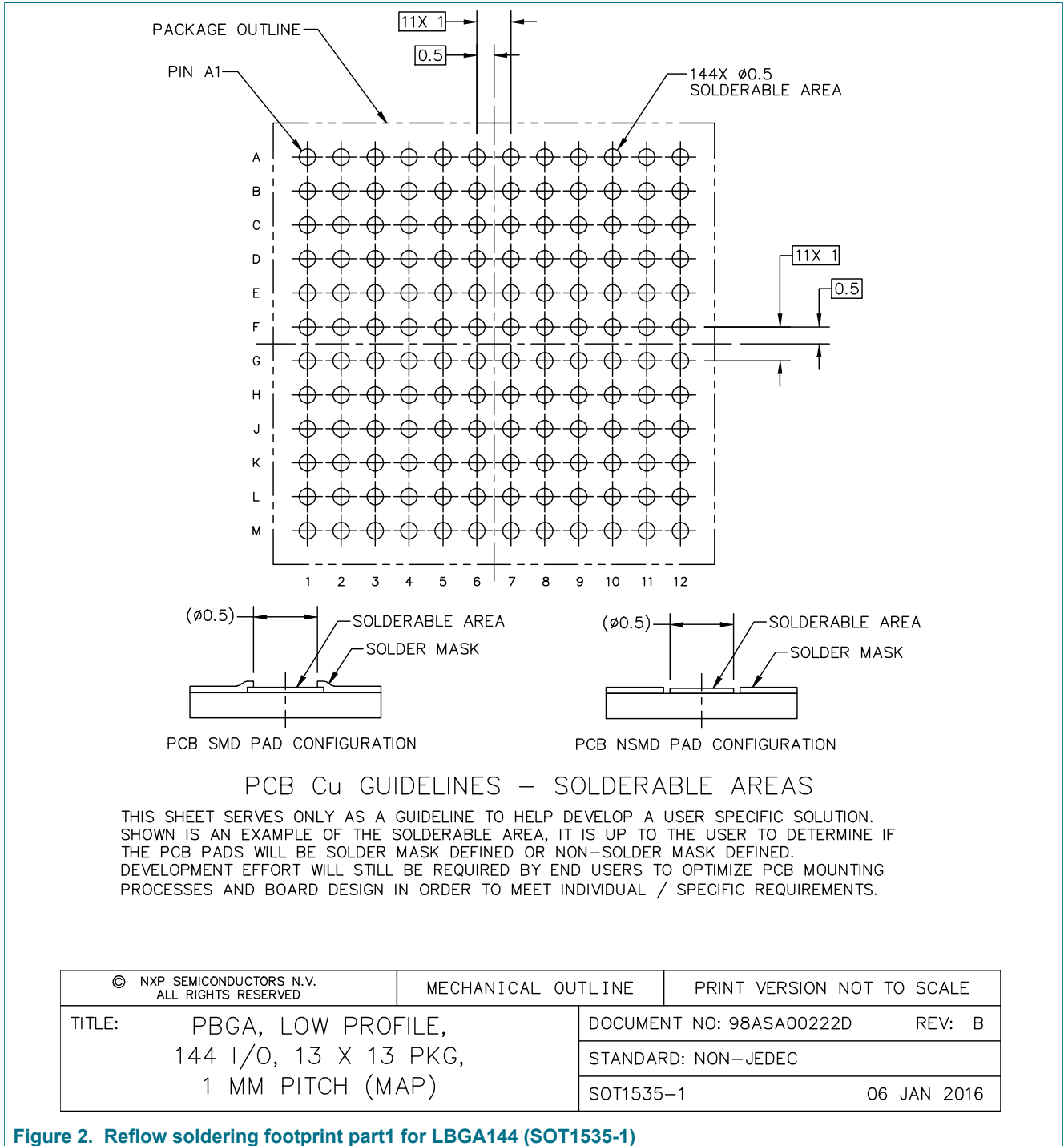


Figure 2. Reflow soldering footprint part1 for LPGA144 (SOT1535-1)

LBGA144; plastic, low profile ball grid array; 144 balls; 1.0 mm pitch; 13 mm x 13 mm x 1.7 mm body

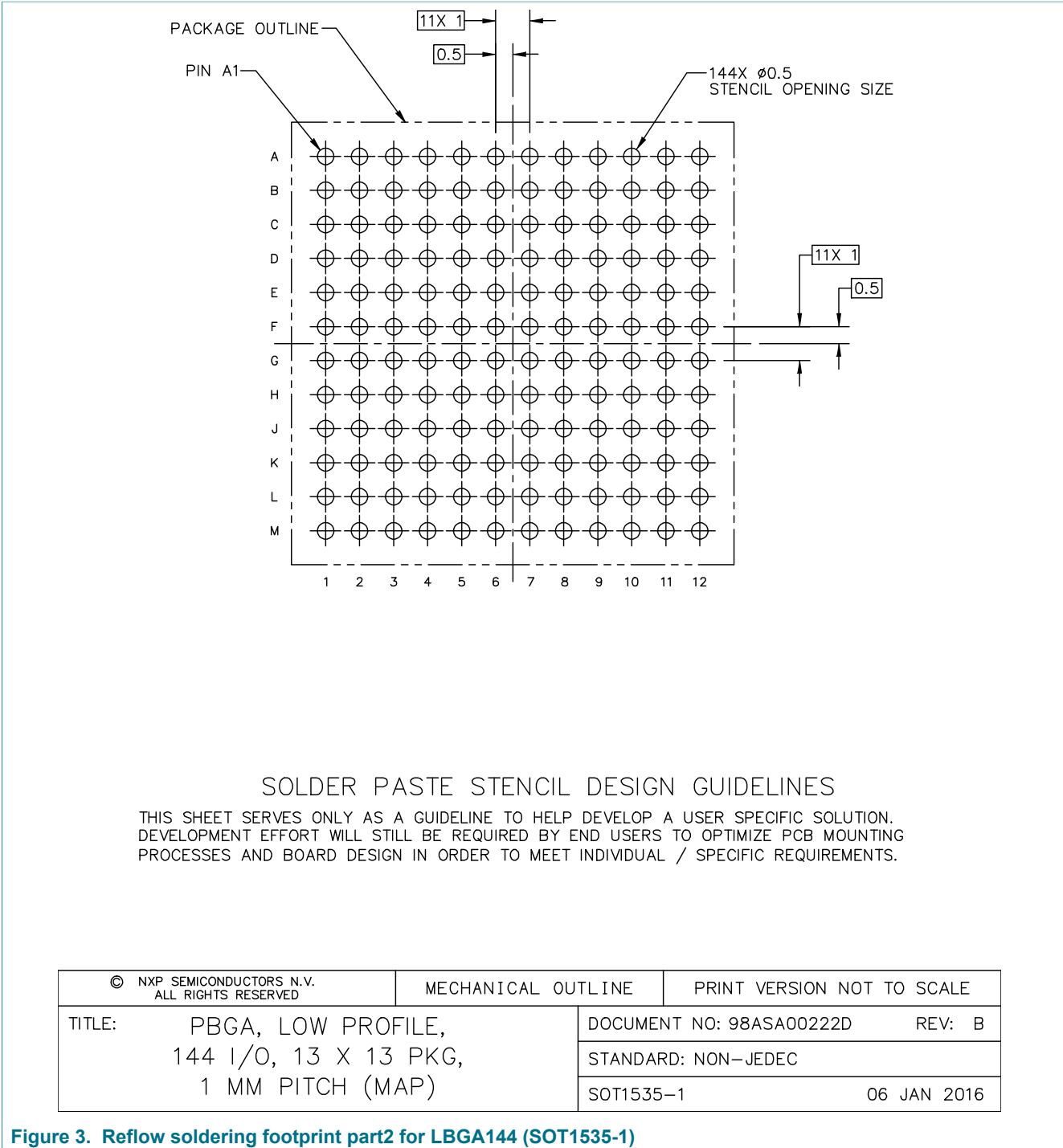


Figure 3. Reflow soldering footprint part2 for LBGA144 (SOT1535-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: PBGA, LOW PROFILE, 144 I/O, 13 X 13 PKG, 1 MM PITCH (MAP)	DOCUMENT NO: 98ASA00222D		REV: B
	STANDARD: NON-JEDEC		
	SOT1535-1		06 JAN 2016

Figure 4. Package outline note LBGA144 (sot1535-1)

4 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Contents

1 Package summary1
2 Package outline2
3 Soldering3
4 Legal information6